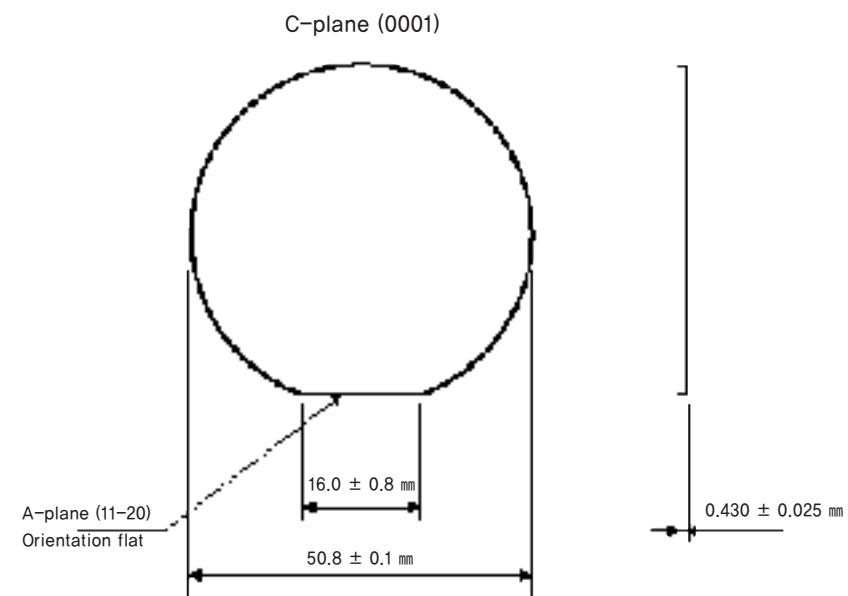
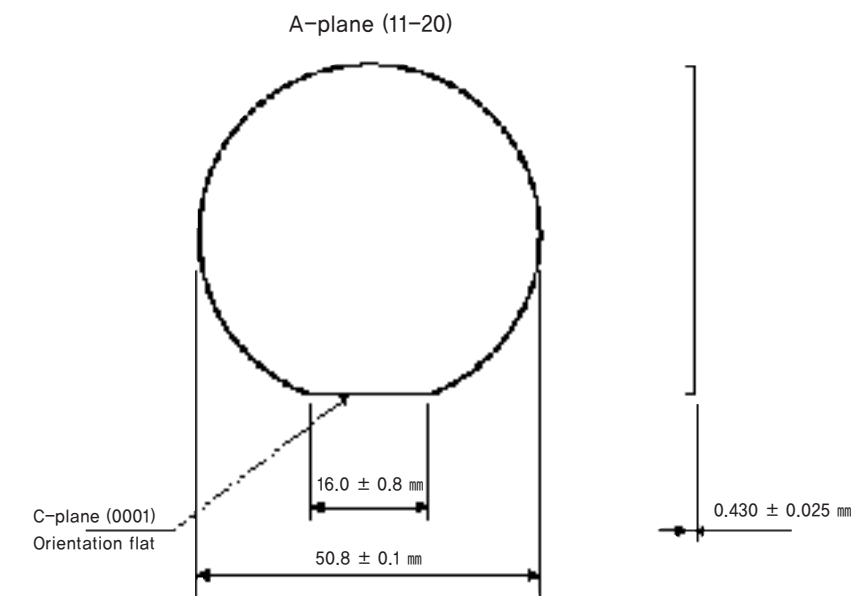


SAPPHIRE WAFER 2 inch C-plane



Property	Specification
Surface Orientation	C-plane (0001)
M-axis Tilt Angle	0.0 ± 0.1°, 0.2 or 0.3 ± 0.05°
Diameter	50.8 ± 0.1 mm
Thickness	0.430 ± 0.025 mm
Bow	≤ 10 μm
TTV	≤ 5 μm
Roughness (Ra)	≤ 0.3 nm
Orientation Flat	A-plane (11-20) ± 0.3°
Flat Length	16.0 ± 0.8 mm
Front Surface Finish	Epi-ready
Back Surface Finish	As-lapped (SSP) or Epi-ready (DSP)

SAPPHIRE WAFER 2 inch A-plane



Property	Specification
Surface Orientation	A-plane (11-20)
M-axis Tilt Angle	0.0 ± 0.1°
C-axis Tilt Angle	0.0 ± 0.1°
Diameter	50.8 ± 0.1 mm
Thickness	0.430 ± 0.025 mm
Bow	≤ 10 μm
TTV	≤ 5 μm
Roughness (Ra)	≤ 0.3 nm
Orientation Flat	C-plane (0001) ± 0.3°
Flat Length	16.0 ± 0.8 mm
Front Surface Finish	Epi-ready
Back Surface Finish	As-lapped (SSP) or Epi-ready (DSP)